

Materials Declaration Form

IPC	1752	Version	2			
Form Type *	Distribute	Tersion.	2			
Sectionals *	Material Info	Subsectionals *	A-D			
	Manufacturing Info		* : Required Field			

Supplier Information								
Company Name *	STMicroelectronics	Response Date *	2018-07-12					
Company Unique ID	NL 008751171B01							
Contact Name *	Refer to Supplier Comment section	•	Refer to Supplier Comment section					
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section					
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION					
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section					
Supplier Comment		nline Technical Support - STMicroelectronics : tp://www.st.com/web/en/support/support.html						

Uncertainty Statement

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Supplier Acceptance * true Legal Declaration * Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product									
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date					
STM32H743VIH6	STM32H743VIH6 P0DY*450XXXY		9996	2018-07-12					
	Amount	UoM	Unit type	ST ECOPACK Grade					
	126.00	mg	Each	ECOPACK® 2					
		ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardar (in each organic material)							

Manufacturing information								
J-STD-020 MSL Rating	J-STD-020 MSL Rating Classification Temp Nbr of Reflow Cycles							
3	260	3						
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	life.augmented				
Not Applicable; if coating is used or other bulk termination	NAC	Copper Alloy						

Package Designator	Size	Nbr of instances	Shape			
BGA	8x8	183	No lead			
Comment	Package : A08Q TFBGA 8X8 100L F10X10 0.8 MM P DM00254729					

QueryList: RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015								
	Query Response							
1 - Product(s) meets EU RoHS requirement without any exemptions								
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may								
apply)		FALSE						
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) FALSE								
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions								
Exemption Id. Description								

QueryList: REACH-27th June 2018								
Query Response								
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH								
CategoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application								

aterial Composition Declaration : te : Substance present with less 0.001mg will not be declared in this document		Mfr Item Name	P0DY*450XXXY				5999999.0	1000000.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.485	mg	supplier	die	Silicon (Si)	7440-21-3		9.743	mg	929232	77325
				supplier	metallization	Aluminium (AI)	7429-90-5		0.088	mg	8393	698
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	26323	2190
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	95	8
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	4292	357
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	763	63
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	95	8
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	30806	2563
SUBSTRATE (DS7409HGB)	M-011 Other inorganic materials	30.380	mg	supplier	CORE	Glass Cloth	65997-17-3		2.560	mg	84270	20318
				supplier	CORE	Copper (Cu)	7440-50-8		6.400	mg	210675	50796
				supplier	CORE	Ероху	28906-96-9		0.896	mg	29494	7111
				supplier	CORE	Flame resistant resin	223769-10-6		0.640	mg	21067	5080
				supplier	CORE	Heat resistant resin	25722-66-1		0.640	mg	21067	5080
				supplier	CORE	Silica filler	7631-86-9		1.152	mg	37921	9143
				supplier	CORE	Metal Hydroxide	Proprietary		0.512	mg	16854	4064
				supplier	SOLDERMASK (AUS320)	Solvent naphtha (petroleum), Heavy arom.	64742-94-5		1.666	mg	54855	13226
				supplier	SOLDERMASK (AUS320)	Naphthalene	91-20-3		0.176	mg	5785	1395
				supplier	SOLDERMASK (AUS320)	Phosphinoxide derivative	Proprietary		0.061	mg	1995	481
				supplier	SOLDERMASK (AUS320)	Talc containing no asbestiform fibers	14807-96-6		0.454	mg	14960	3607
				supplier	SOLDERMASK (AUS320)	Barium sulfate	7727-43-7		0.757	mg	24934	6012
				supplier	SOLDERMASK (AUS320)	Dipropylene glycol monomethyl ether	34590-94-8		0.454	mg	14960	3607
				supplier	CU FOIL	Copper (Cu)	7440-50-8		13.114	mg	431649	104075
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		0.737	mg	24253	5848
				supplier	AU PLATING	Gold (Au)	7440-57-5		0.160	mg	5260	1268
DIE ATTACH (2300)	M-011 Other inorganic materials	1.478	mg	supplier	GLUE	Silver (Ag)	7440-22-4		1.404	mg	950000	11142
				supplier	GLUE	Tetramethylene dimethacrylate	2082-81-7		0.074	mg	50000	586
BONDING WIRE (Au wire)	M-011 Other inorganic materials	1.197	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.197	mg	1000000	9499
SOLDERBALL (SAC 105)	M-011 Other inorganic materials	35.598	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		35.064	mg	985000	278283
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.356	mg	10000	2825
				supplier	SOLDERBALL	Copper (Cu)	7440-50-8		0.178	mg	5000	1413
ENCAPSULATION (GE-100LFCS)	M-011 Other inorganic materials	46.863	mg	supplier	MOLDING COMPOUND	Silica vitreous	60676-86-0		41.409	mg	885000	328645
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		1.897	mg	40000	15055
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		1.423	mg	30000	11291
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.237	mg	5000	1882
				supplier	MOLDING COMPOUND	Metal hydroxide	Proprietary		1.423	mg	30000	11291
				supplier	MOLDING COMPOUND	Crystalline silica	14808-60-7		0.474	mg	10000	3764